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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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InGaP HBT 5GHz Power Amplifier Abridged Datasheet

Description

The LX5509 is a power amplifier optimized for 802.11ac/a/n applications in the 5.15-5.85 GHz frequency range. The LX5509 includes a three-stage PA, active bias, input/output matching, and a harmonic filter.

The device is manufactured with an InGaP/GaAs Heterojunction Bipolar Transistor (HBT) IC process (MOCVD). It operates with a single positive voltage supply of 3.3V, and provides power gain of 28dB and output powers of 19-20 and 19.5-20.5 dBm at 3.3V across the frequency band for 1.8 and 3% dynamic EVM(DEVM), respectively.

The 2nd and 3rd harmonics are lower than -45dBm/MHz over the frequency band due to an integrated harmonic filter. The LX5509 also features an on-chip power detector to help reduce BOM cost and PCB space for implementation of power control in a typical wireless system.

The LX5509 is available in a 20-pin 4mm x 4mm quad flat no lead package (QFN 4×4 -20L). The compact footprint, low profile, and excellent thermal capability make the LX5509 an ideal solution for 802.11ac/a/n applications.

Features

- ♦ Advanced InGaP HBT
- ♦ 5.15-5.85GHz Operation
- ♦ Single-Polarity 3.3V Supply
- ♦ Power Gain ~ 28dB
- ♦ 19-20dBm @1.8%DEVM for 802.11ac
- ♦ 19.5-20.5dBm @3%DEVM for 802.11a
- ♦ <-45dBm/MHz for 2nd Harmonic
- ♦ <-45dBm/MHz for 3rd Harmonic
- ♦ Complete Input/Output Match
- Temperature-Compensated
- ♦ On-Chip Output Power Detector
- ♦ Small Footprint: 4x4mm²
- ♦ Low Profile: 0.9mm
- RoHS Compliant for Pb-free

Applications

802.ac/a/n

